

The APFEL ASIC Project Next Steps

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Where we are

- Development since 2005 with three prototype iterations
- 2nd iteration already fulfills the given requirements for the preamplifier and shaper
- 3rd iteration with identical analogue part
 - 200 ASICs available for detector tests
 - delivery on April 7th

Comparison of 2nd and 3rd Iteration

2nd Iteration	3rd Iteration
Well specified analogue part fulfils all known requirements	No changes in analogue part; identical layout
High and low gain output are not usable simultaneously due to mismatch in DC-Level	Additional reference voltage generated by a third DAC to adjust DC levels of both outputs independantly
Some experience needed to find correct DAC settings	Autocalibration
	Digital readout of DAC settings
3.3 x 3.3 mm ² , 64 Bondpads	3.3 x 3.4 mm ² , 64 Bondpads Pinout differs from 2nd Iteration !

APFEL Test Status

- 2nd Iteration
 - Lab-measurements:
 - Noise (as function of temperatur and detector capacitance)
 - Power consumption (as function of temperatur and hit rate)
 - Shaping time
 - Dynamic range
 - ...
 - Tests at KVI
 - Time resolution
 - Matrix of 16 crystals with sampling ADC readout
 - Successful cosmic test at -20°C
 - Testsetup available for beam tests
 - 10 ASICs at KVI for test with the PC board prototype
- 3rd Iteration: Just delivered...

APFEL - 3rd Iteration

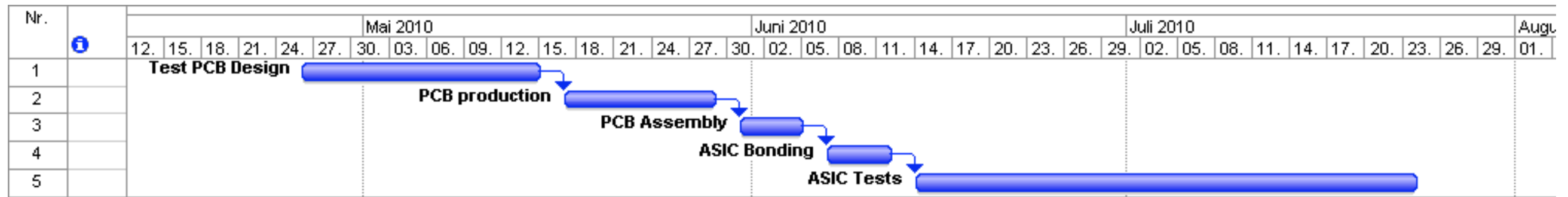
- APFEL Order:

Insitute	Project	Number of ASICs
Uni Bochum	Proto 192	50
Uni Mainz	Backward Endcap	50
Uppsala		25
KVI	PCB Prototypes	20
Basel		3
Warsaw	Low Energy Measurements	4
GSI	ASIC Development	20
Uni München	Electronic Tests	2
Summ		174

APFEL - 3rd Iteration

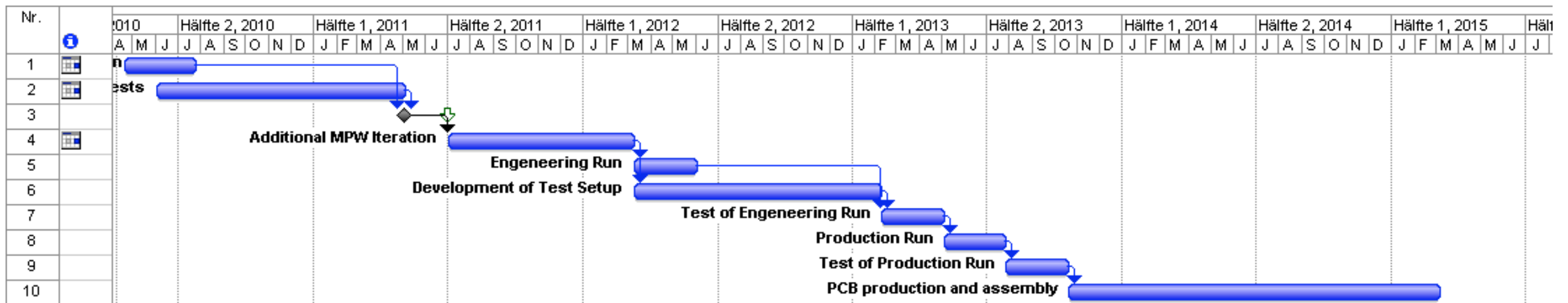
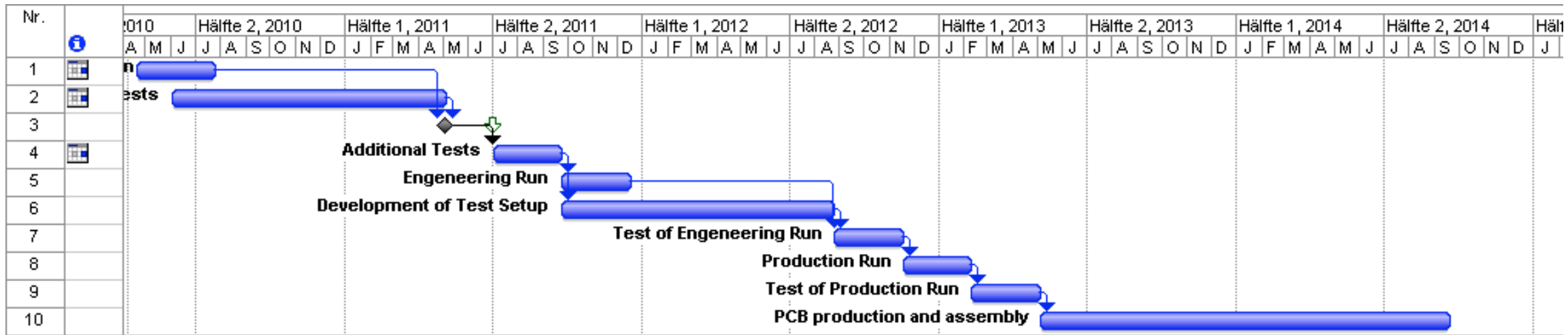
- Support from GSI ASIC-Design
 - Documentation
 - Packaging (only for few pieces (< 5))
 - PCB development
 - Design rules for PCB footprint
 - Coating specification for bond process
 - If applicable design of a common use test PCB

The Next Steps



- 3rd iteration has to be tested and specified
- Time estimation:
 - First test results in June
 - Complete ASIC specification end of July

Schedule for Production



- Design readiness review midyear 2011
 - more than 12 months for detector tests
- Readout electronics ready for detector integration: 2014 - 2015